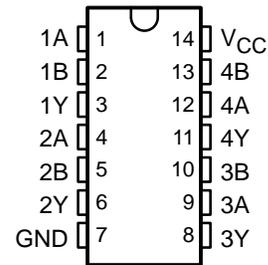


# CD54AC32, CD74AC32 QUADRUPLE 2-INPUT POSITIVE-OR GATES

SCHS343 – MARCH 2003

- AC Types Feature 1.5-V to 5.5-V Operation and Balanced Noise Immunity at 30% of the Supply
- Buffered Inputs
- Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption
- Balanced Propagation Delays
- $\pm 24$ -mA Output Drive Current  
– Fanout to 15 F Devices
- SCR-Latchup-Resistant CMOS Process and Circuit Design
- Exceeds 2-kV ESD Protection Per MIL-STD-883, Method 3015

CD54AC32 . . . F PACKAGE  
CD74AC32 . . . E OR M PACKAGE  
(TOP VIEW)



## description/ordering information

The 'AC32 devices are quadruple 2-input positive-OR gates. These devices perform the Boolean function  $Y = \overline{\overline{A} \cdot \overline{B}}$  or  $Y = A + B$  in positive logic.

## ORDERING INFORMATION

T <sub>A</sub>	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–55°C to 125°C	PDIP – E	Tube	CD74AC32E	CD74AC32E
	SOIC – M	Tube	CD74AC32M	AC32M
		Tape and reel	CD74AC32M96	
	CDIP – F	Tube	CD54AC32F3A	CD54AC32F3A

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

## FUNCTION TABLE (each gate)

INPUTS		OUTPUT
A	B	Y
H	X	H
X	H	H
L	L	L



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS  
INSTRUMENTS**

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# CD54AC32, CD74AC32 QUADRUPLE 2-INPUT POSITIVE-OR GATES

SCHS343 – MARCH 2003

## logic diagram (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$ .....	-0.5 V to 6 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1) .....	$\pm 20$ mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) (see Note 1) .....	$\pm 50$ mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ ) .....	$\pm 50$ mA
Continuous current through $V_{CC}$ or GND .....	$\pm 100$ mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): E package .....	80°C/W
M package .....	86°C/W
Storage temperature range, $T_{stg}$ .....	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JESD 51-7.

## recommended operating conditions (see Note 3)

		$T_A = 25^\circ\text{C}$		$-55^\circ\text{C to } 125^\circ\text{C}$		$-40^\circ\text{C to } 85^\circ\text{C}$		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
$V_{CC}$	Supply voltage	1.5	5.5	1.5	5.5	1.5	5.5	V
$V_{IH}$	High-level input voltage	$V_{CC} = 1.5\text{ V}$		1.2		1.2		V
		$V_{CC} = 3\text{ V}$		2.1		2.1		
		$V_{CC} = 5.5\text{ V}$		3.85		3.85		
$V_{IL}$	Low-level input voltage	$V_{CC} = 1.5\text{ V}$		0.3		0.3		V
		$V_{CC} = 3\text{ V}$		0.9		0.9		
		$V_{CC} = 5.5\text{ V}$		1.65		1.65		
$V_I$	Input voltage	0	$V_{CC}$	0	$V_{CC}$	0	$V_{CC}$	V
$V_O$	Output voltage	0	$V_{CC}$	0	$V_{CC}$	0	$V_{CC}$	V
$I_{OH}$	High-level output current	$V_{CC} = 4.5\text{ V to } 5.5\text{ V}$		-24		-24		mA
$I_{OL}$	Low-level output current	$V_{CC} = 4.5\text{ V to } 5.5\text{ V}$		24		24		mA
$\Delta t/\Delta v$	Input transition rise or fall rate	$V_{CC} = 1.5\text{ V to } 3\text{ V}$		50		50		ns/V
		$V_{CC} = 3.6\text{ V to } 5.5\text{ V}$		20		20		

NOTE 3: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS		V <sub>CC</sub>	T <sub>A</sub> = 25°C		–55°C to 125°C		–40°C to 85°C		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = –50 μA	1.5 V	1.4	1.4	1.4			V	
			3 V	2.9	2.9	2.9				
			4.5 V	4.4	4.4	4.4				
		I <sub>OH</sub> = –4 mA	3 V	2.58	2.4	2.48				
		I <sub>OH</sub> = –24 mA	4.5 V	3.94	3.7	3.8				
		I <sub>OH</sub> = –50 mA <sup>†</sup>	5.5 V		3.85					
I <sub>OH</sub> = –75 mA <sup>†</sup>	5.5 V			3.85						
V <sub>OL</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> = 50 μA	1.5 V		0.1	0.1		0.1	V	
			3 V		0.1	0.1		0.1		
			4.5 V		0.1	0.1		0.1		
		I <sub>OL</sub> = 12 mA	3 V		0.36	0.5		0.44		
		I <sub>OL</sub> = 24 mA	4.5 V		0.36	0.5		0.44		
		I <sub>OL</sub> = 50 mA <sup>†</sup>	5.5 V			1.65				
I <sub>OL</sub> = 75 mA <sup>†</sup>	5.5 V					1.65				
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND		5.5 V		±0.1	±1	±1	μA		
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0		5.5 V		4	80	40	μA		
C <sub>i</sub>					10	10	10	pF		

<sup>†</sup> Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.

**switching characteristics over recommended operating free-air temperature range, V<sub>CC</sub> = 1.5 V, C<sub>L</sub> = 50 pF (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55°C to 125°C		–40°C to 85°C		UNIT
			MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A or B	Y		119		108	ns
t <sub>PHL</sub>				119		108	

**switching characteristics over recommended operating free-air temperature range, V<sub>CC</sub> = 3.3 V ± 0.3 V, C<sub>L</sub> = 50 pF (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55°C to 125°C		–40°C to 85°C		UNIT
			MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A or B	Y	3.3	13.3	3.4	12.1	ns
t <sub>PHL</sub>			3.3	13.3	3.4	12.1	

# CD54AC32, CD74AC32 QUADRUPLE 2-INPUT POSITIVE-OR GATES

SCHS343 – MARCH 2003

switching characteristics over recommended operating free-air temperature range,  
 $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ ,  $C_L = 50\text{ pF}$  (unless otherwise noted) (see Figure 1)

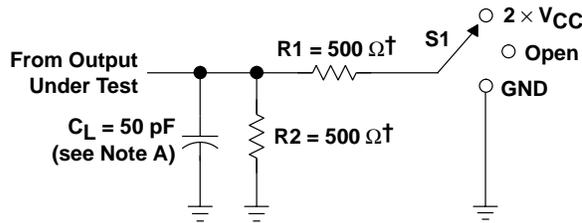
PARAMETER	FROM (INPUT)	TO (OUTPUT)	-55°C to 125°C		-40°C to 85°C		UNIT
			MIN	MAX	MIN	MAX	
tPLH	A or B	Y	2.4	9.5	2.4	8.6	ns
tPHL			2.4	9.5	2.4	8.6	

operating characteristics,  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$

PARAMETER		TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	47	pF



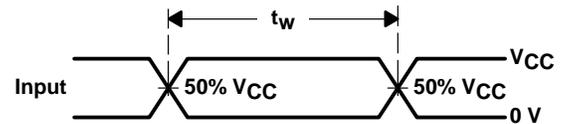
PARAMETER MEASUREMENT INFORMATION



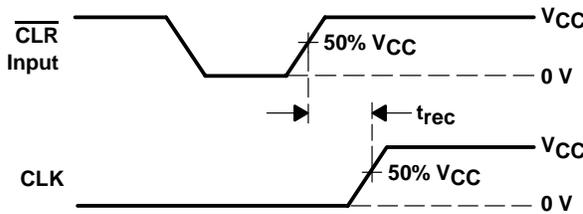
† When  $V_{CC} = 1.5\text{ V}$ ,  $R_1 = R_2 = 1\text{ k}\Omega$

LOAD CIRCUIT

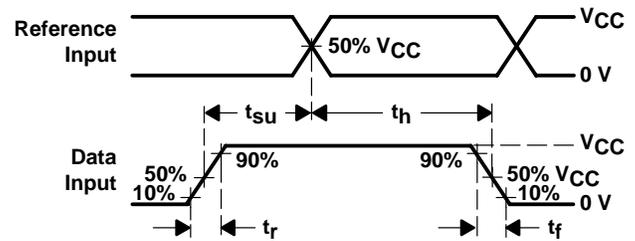
TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$2 \times V_{CC}$
$t_{PHZ}/t_{PZH}$	GND



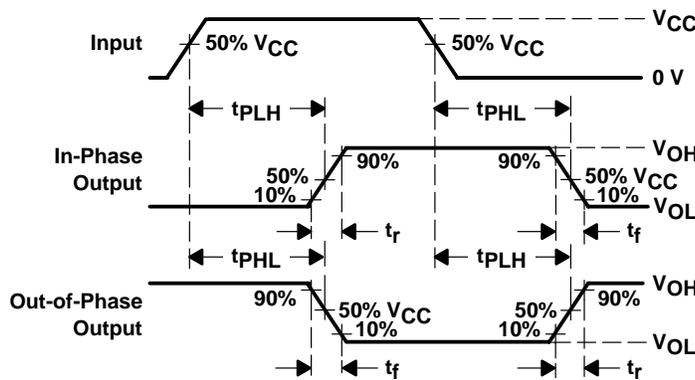
VOLTAGE WAVEFORMS  
PULSE DURATION



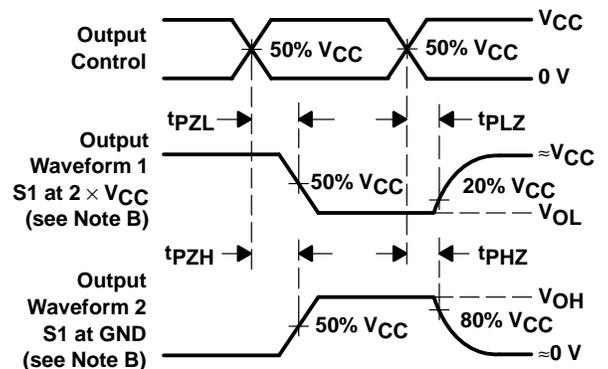
VOLTAGE WAVEFORMS  
RECOVERY TIME



VOLTAGE WAVEFORMS  
SETUP AND HOLD AND INPUT RISE AND FALL TIMES



VOLTAGE WAVEFORMS  
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES



VOLTAGE WAVEFORMS  
OUTPUT ENABLE AND DISABLE TIMES

- NOTES: A.  $C_L$  includes probe and test-fixture capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r = 3\text{ ns}$ ,  $t_f = 3\text{ ns}$ . Phase relationships between waveforms are arbitrary.  
 D. For clock inputs,  $f_{max}$  is measured with the input duty cycle at 50%.  
 E. The outputs are measured one at a time with one input transition per measurement.  
 F.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .  
 G.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .  
 H.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .  
 I. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CD54AC32F3A	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD54AC32F3A	<a href="#">Samples</a>
CD74AC32E	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74AC32E	<a href="#">Samples</a>
CD74AC32EE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74AC32E	<a href="#">Samples</a>
CD74AC32M	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC32M	<a href="#">Samples</a>
CD74AC32M96	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC32M	<a href="#">Samples</a>
CD74AC32M96E4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC32M	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF CD54AC32, CD74AC32 :**

- Catalog : [CD74AC32](#)
- Military : [CD54AC32](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**

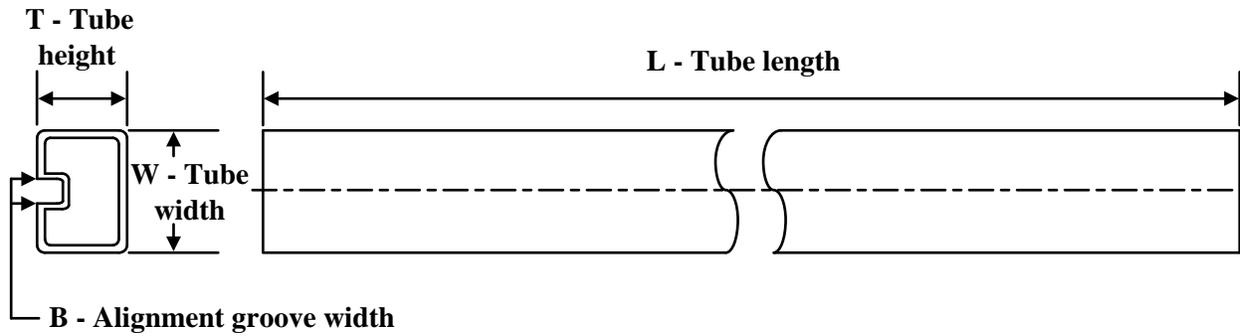

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74AC32M96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74AC32M96	SOIC	D	14	2500	356.0	356.0	35.0

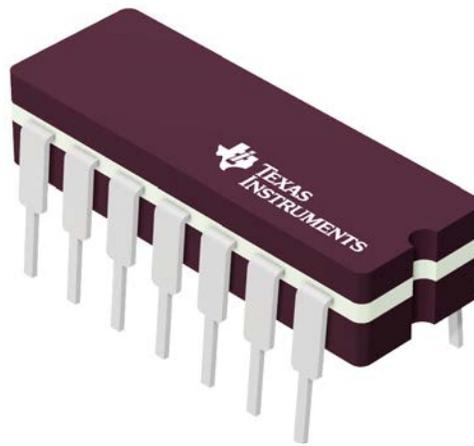
**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
CD74AC32E	N	PDIP	14	25	506	13.97	11230	4.32
CD74AC32E	N	PDIP	14	25	506	13.97	11230	4.32
CD74AC32EE4	N	PDIP	14	25	506	13.97	11230	4.32
CD74AC32EE4	N	PDIP	14	25	506	13.97	11230	4.32
CD74AC32M	D	SOIC	14	50	506.6	8	3940	4.32

J 14

**GENERIC PACKAGE VIEW**  
**CDIP - 5.08 mm max height**  
CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4040083-5/G

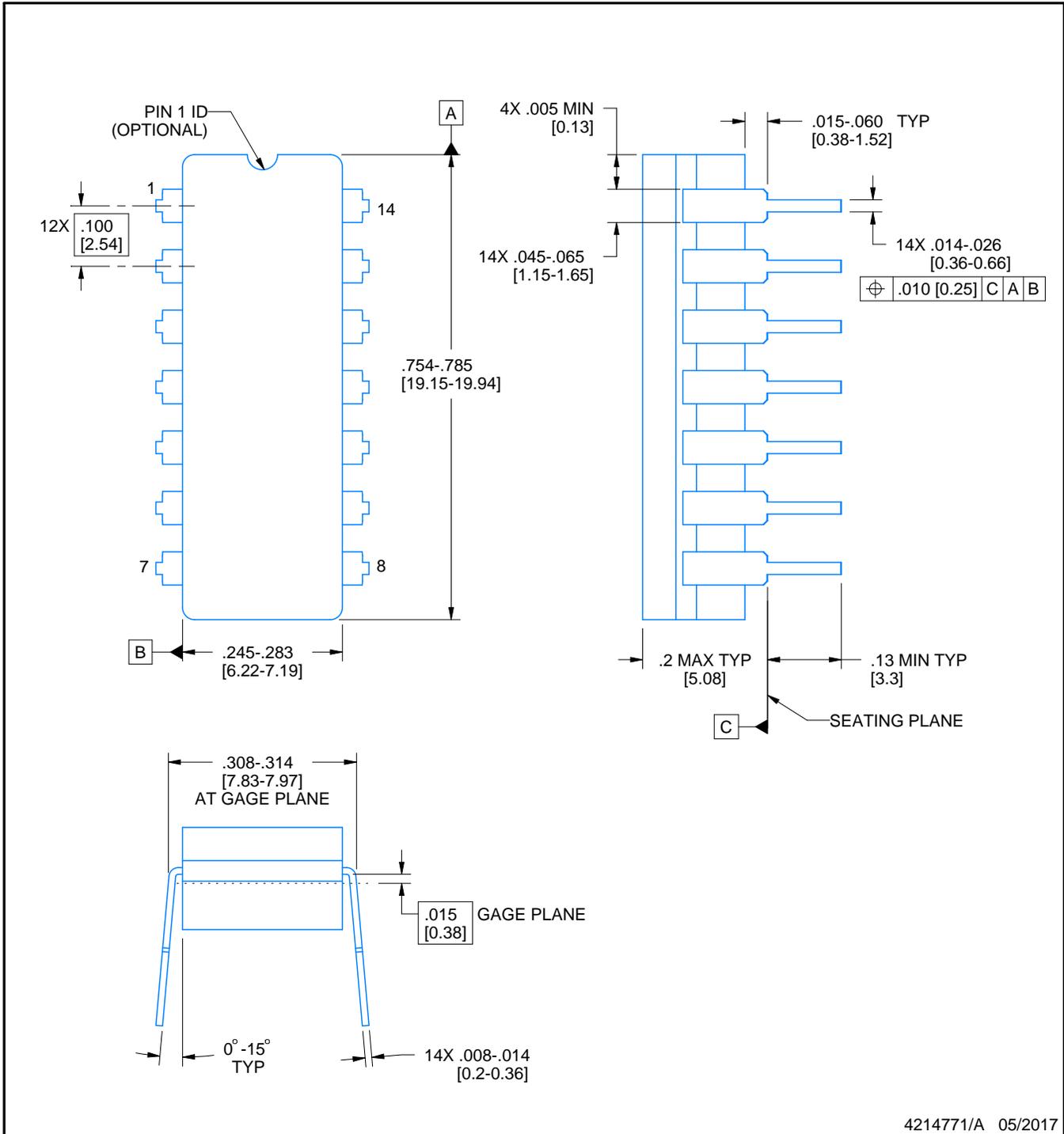
J0014A



# PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

NOTES:

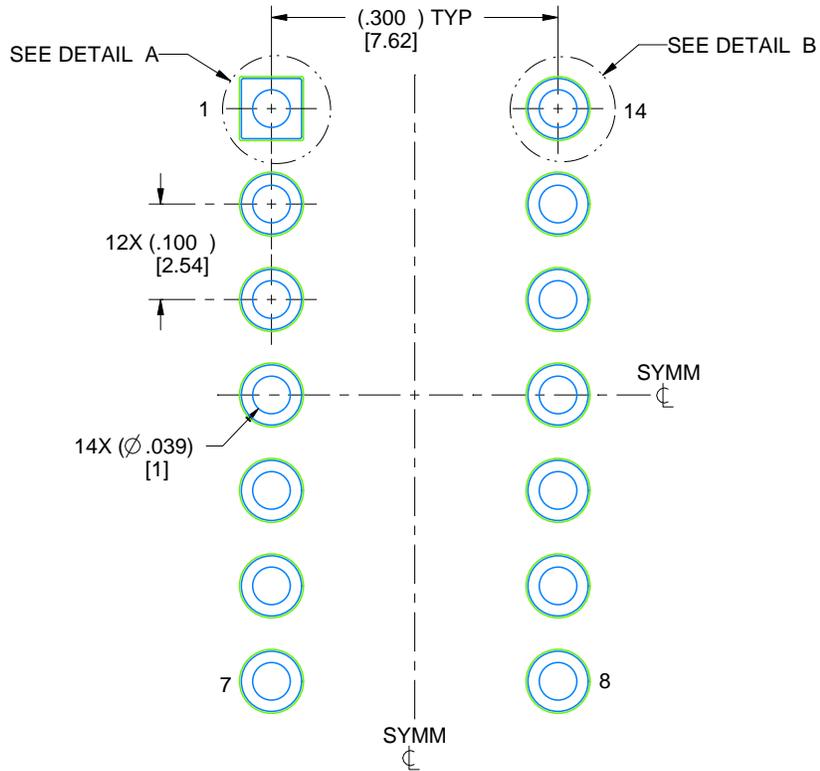
1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

# EXAMPLE BOARD LAYOUT

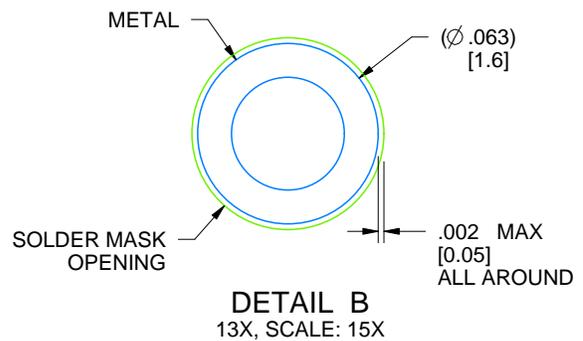
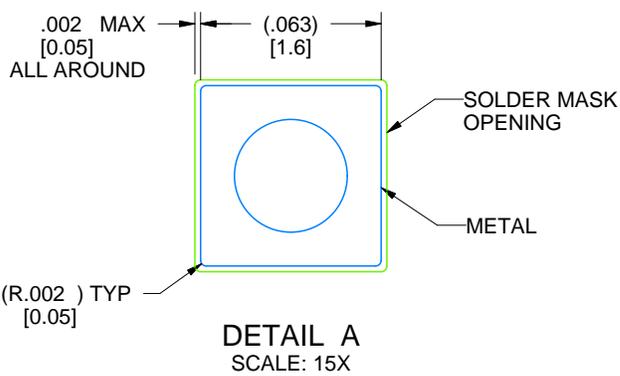
J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



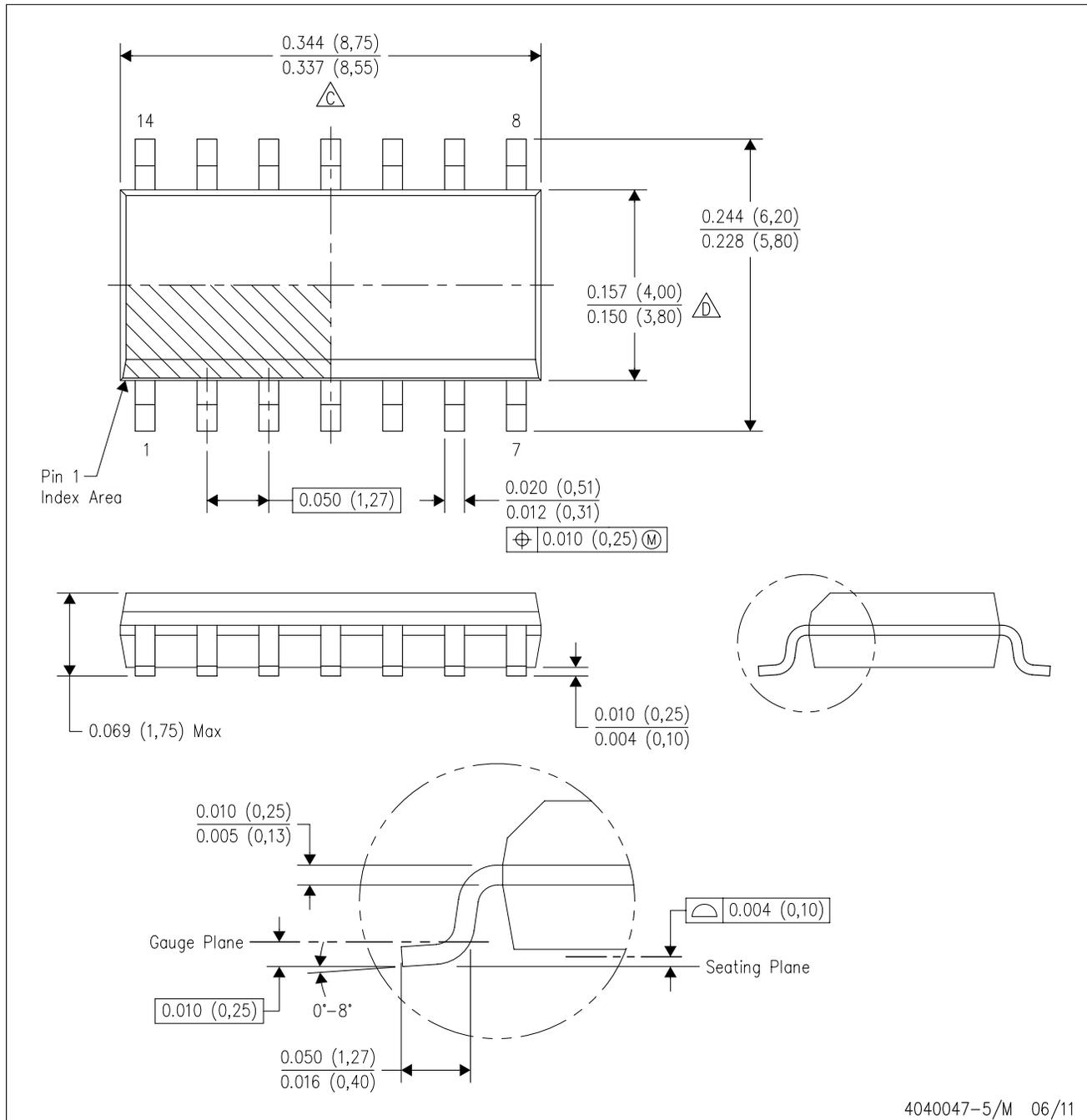
LAND PATTERN EXAMPLE  
NON-SOLDER MASK DEFINED  
SCALE: 5X



4214771/A 05/2017

D (R-PDSO-G14)

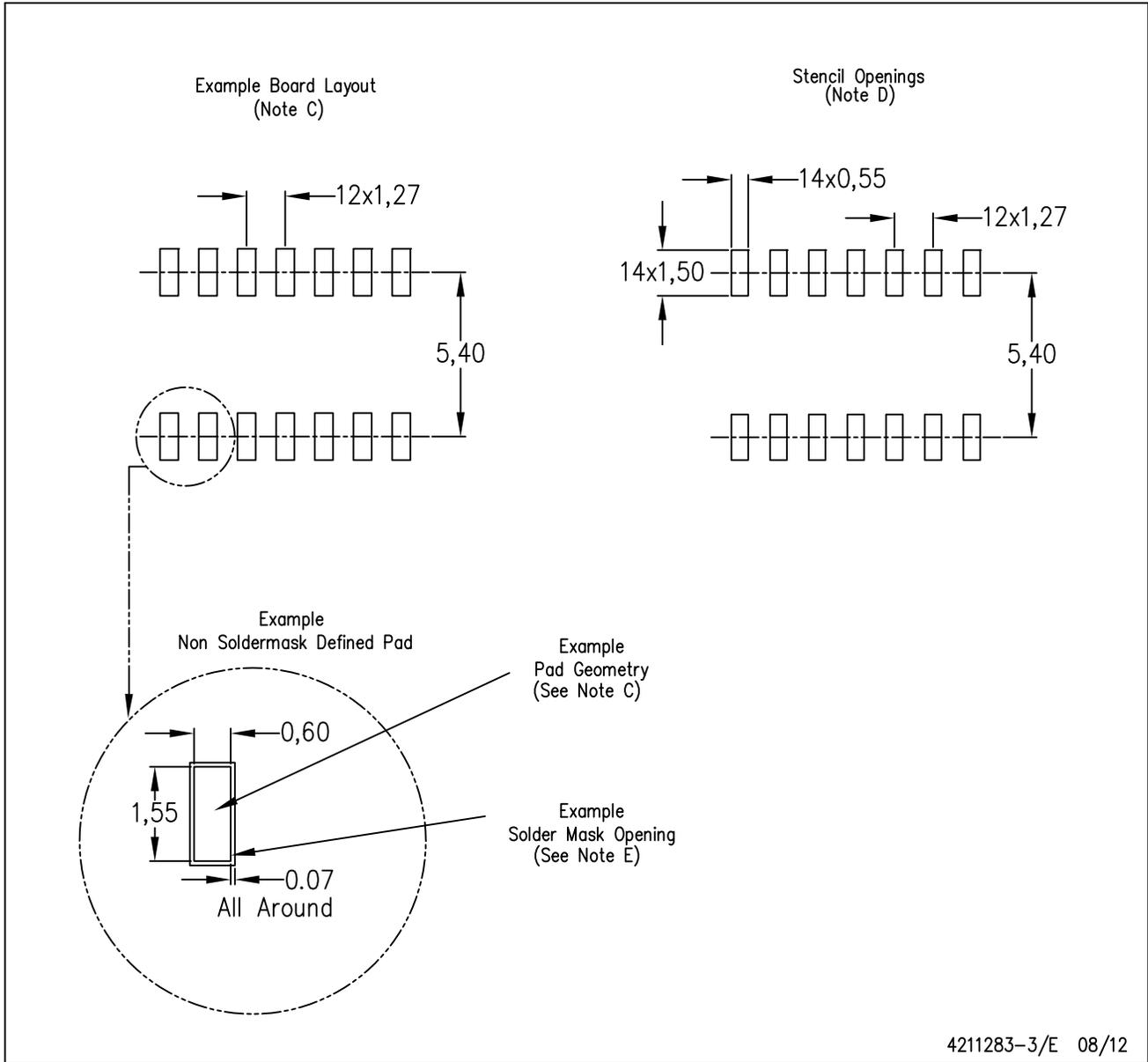
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

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